BTA216X series B

GENERAL DESCRIPTION

Glass passivated high commutation triacs in a full pack, plastic envelope intended for use in circuits where high static and dynamic dV/dt and high dl/dt can occur. These devices will commutate the full rated rms current at the maximum rated junction temperature, without the aid of a snubber.

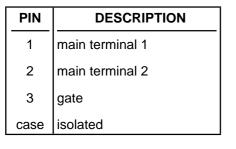
PINNING - SOT186A

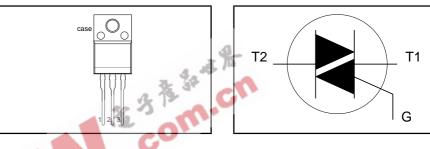
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
V _{drm} I _{t(rms)} I _{tsm}	BTA216X- Repetitive peak off-state voltages RMS on-state current Non-repetitive peak on-state current	500B 500 16 140	600B 600 16 140	800B 800 16 140	V A A

PIN CONFIGURATION

SYMBOL





LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
V _{DRM}	Repetitive peak off-state voltages		-	-500 500 ¹	-600 600 ¹	-800 800	V
I _{T(RMS)}	RMS on-state current	full sine wave;	-		16		A
I _{TSM}	Non-repetitive peak on-state current	$T_{hs} \le 38 \degree C$ full sine wave; $T_j = 25 \degree C$ prior to surge t = 20 ms t = 16.7 ms	-		140		AA
l²t dl _⊤ /dt	I ² t for fusing Repetitive rate of rise of on-state current after triggering		-		150 98 100		A A²s A/µs
$\begin{matrix} I_{GM} \\ V_{GM} \\ P_{GM} \\ P_{G(AV)} \end{matrix}$	Peak gate current Peak gate voltage Peak gate power Average gate power	over any 20 ms period	- - -		2 5 5 0.5		A V W V
T _{stg} T _j	Storage temperature Operating junction temperature		-40 -		150 125		°C °C

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 $A/\mu s$.

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ISOLATION LIMITING VALUE & CHARACTERISTIC

 $T_{hs} = 25$ °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	R.M.S. isolation voltage from all three terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65% ; clean and dustfree	-		2500	V
C _{isol}	Capacitance from T2 to external heatsink	f = 1 MHz	-	10	-	pF

THERMAL RESISTANCES

		MAX.	UNIT
R th j-hsThermal resistance junction to heatsinkfull or half cycle with heatsink compound without heatsink compound in free airR th j-aThermal resistance junction to ambientfull or half cycle with heatsink compound in free air	 - - 55	4.0 5.5 -	K/W K/W K/W

STATIC CHARACTERISTICS

$T_i = 25$ °C unless otherwise stated

	junction to ambient	26	2.8				
STATIC CHARACTERISTICS							
SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current ² Latching current	$V_{\rm D} = 12$ V; $I_{\rm T} = 0.1$ A $V_{\rm D} = 12$ V; $I_{\rm GT} = 0.1$ A	T2+ G+ T2+ G- T2- G- T2+ G+	2 2 2 -	18 21 34 31	50 50 50 60	mA mA mA
I _H V _T V _{GT}	Holding current On-state voltage Gate trigger voltage Off-state leakage current	$V_{D} = 12 \text{ V}; \text{ I}_{GT} = 0.1 \text{ A}$ $I_{T} = 20 \text{ A}$ $V_{D} = 12 \text{ V}; \text{ I}_{T} = 0.1 \text{ A}$ $V_{D} = 400 \text{ V}; \text{ I}_{T} = 0.1 \text{ A}; \text{ T}_{i} = 12$ $V_{D} = V_{DRM(max)}; \text{ T}_{j} = 125 \text{ °C}$	T2+ G- T2- G- 25 °C	- - - 0.25	34 30 31 1.2 0.7 0.4 0.1	90 60 1.5 1.5 - 0.5	mA mA V V V MA

DYNAMIC CHARACTERISTICS

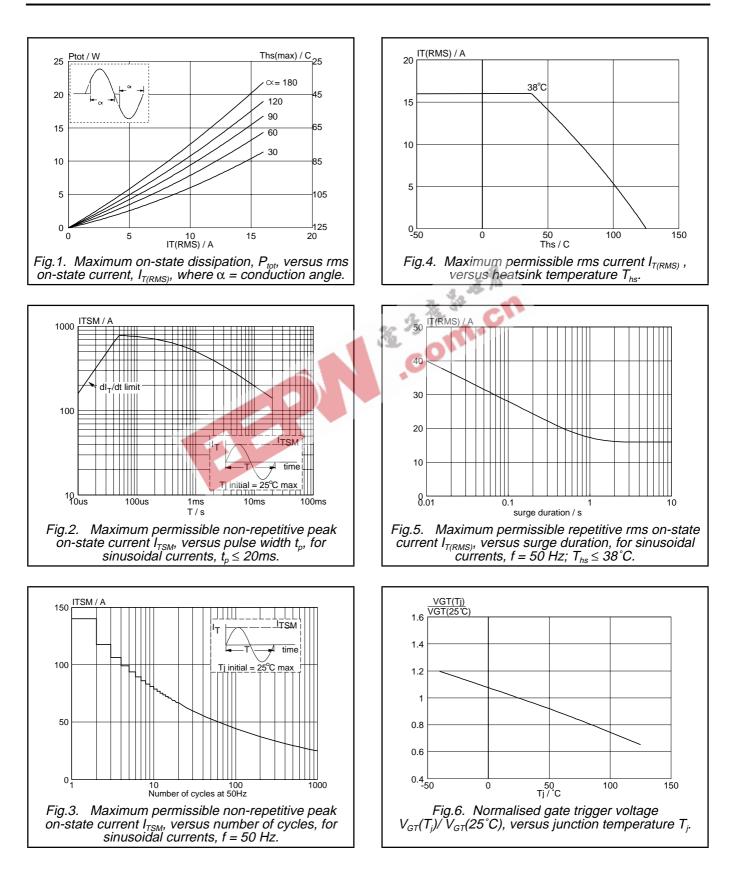
 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$	1000	4000	-	V/µs
dl _{com} /dt	off-state voltage Critical rate of change of commutating current	exponential waveform; gate open circuit $V_{DM} = 400 \text{ V}; \text{ T}_{j} = 125 ^{\circ}\text{C}; \text{ I}_{T(RMS)} = 16 \text{ A};$ without snubber; gate open circuit	-	28	-	A/ms
t _{gt}		$I_{TM} = 20 \text{ A}; V_D = V_{DRM(max)}; I_G = 0.1 \text{ A};$ $dI_G/dt = 5 \text{ A}/\mu\text{s}$	-	2	-	μs

² Device does not trigger in the T2-, G+ quadrant.

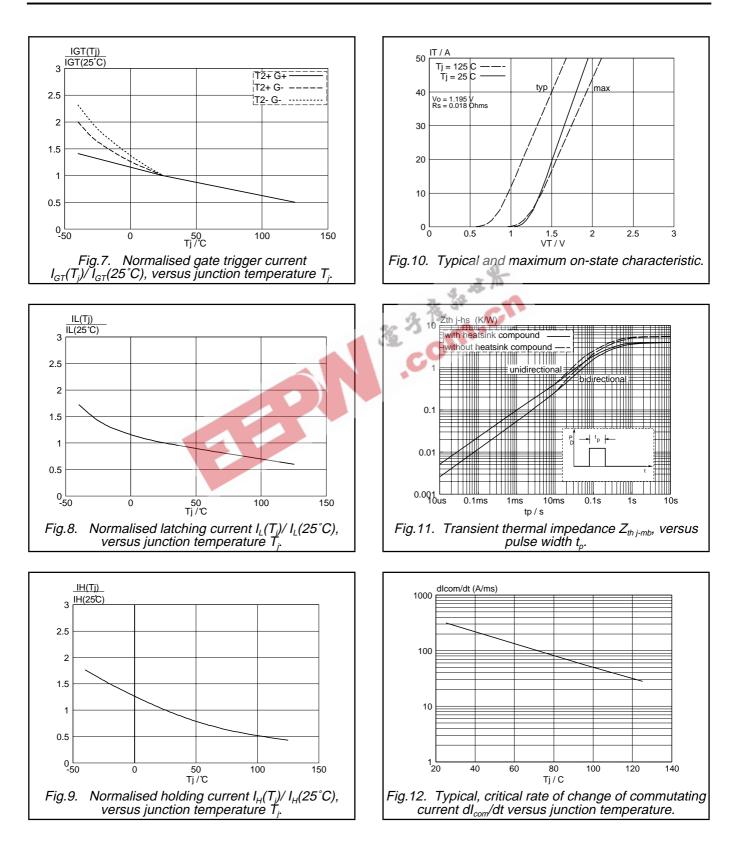
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Three quadrant triacs high commutation



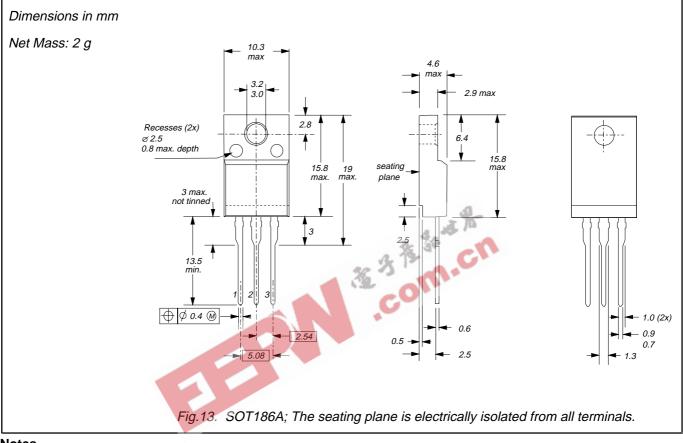
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Three quadrant triacs high commutation



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MECHANICAL DATA



Notes 1. Refer to mounting instructions for F-pack envelopes. 2. Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
Limiting values					
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.					
Application information					
Where application information is given, it is advisory and does not form part of the specification.					
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